

# Interconnection studies for monolithic silicon pixel detector modules using the MALTA CMOS pixel chip

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The material budget in the innermost tracking layers is a critical parameter that strongly influences the impact parameter resolution especially for lower momentum particles. Monolithic silicon pixel detectors can be thinned to typical thicknesses of 100  $\mu\text{m}$  or less, thus providing the possibility to minimize the silicon contribution in the material budget. The MALTA monolithic silicon pixel sensor is a large area radiation hard monolithic CMOS sensor developed in the 0.18  $\mu\text{m}$  CMOS process. It provides the possibility to transfer data and power from chip to chip and first tests using ultrasonic Al-wedge wire bonding have validated this concept to build multi-chip modules. Several interconnection technologies are being studied to provide high quality and mechanically robust direct chip-to-chip connections between different MALTA chips. Transferring data (GHz) and power from chip-to-chip will further contribute to designing a low mass and compact MALTA module. This presentation will present the studies and first findings as well as plans to build a large area module.

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